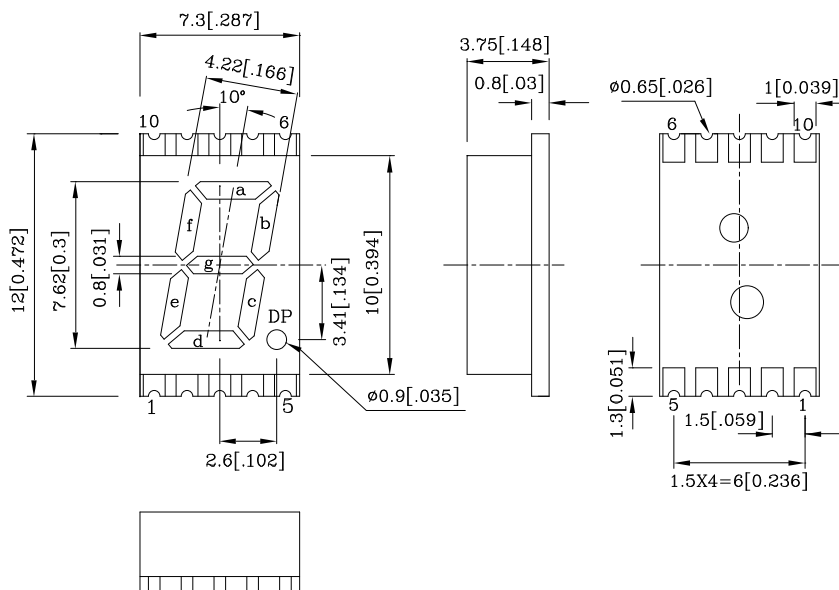
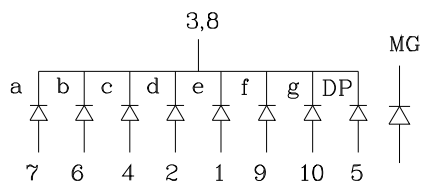


Features

- 0.3 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE,WHITE SEGMENT.
- PACKAGE : 550PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



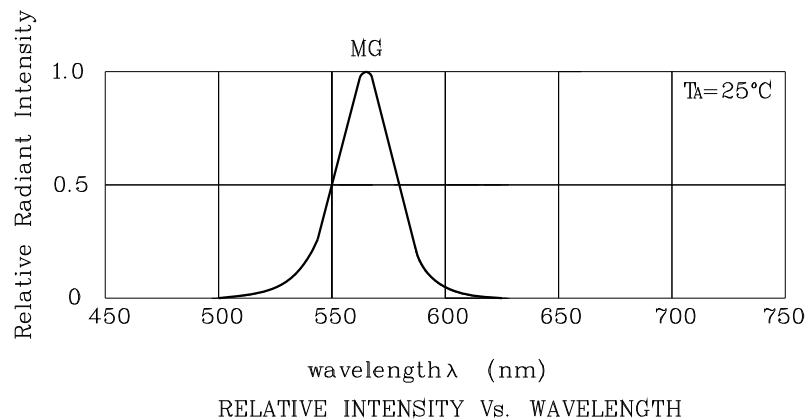
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3.The gap between the reflector and PCB shall not exceed 0.25mm.
4. Specifications are subject to change without notice.

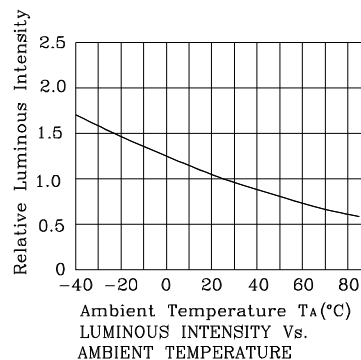
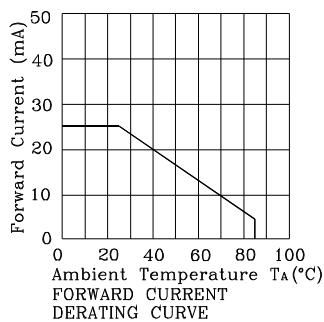
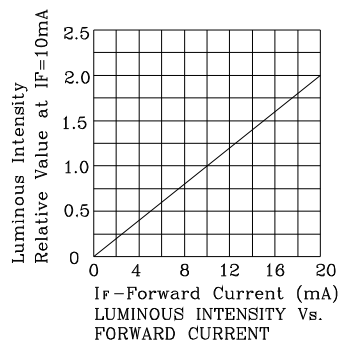
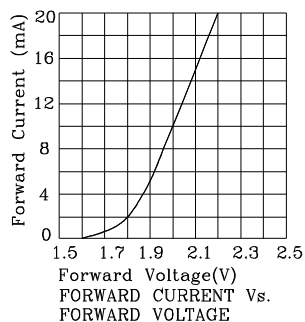
Absolute Maximum Ratings (TA=25°C)		MG (GaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	PT	62.5	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (T _A =25°C)		MG (GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	2.0	V
Forward Voltage (Max.) (I _F =10mA)	V _F	2.5	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength Of Peak Emission (Typ.) (I _F =10mA)	λ P	565	nm
Wavelength Of Dominant Emission (Typ.) (I _F =10mA)	λ D	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	30	nm
Capacitance (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd	Wavelength nm λ P	Description
			min.	typ.	
ZFMG07C	Green	GaP	1200	5590	565 Common Cathode. Rt. Hand Decimal
Published Date : MAR 03,2008		Drawing No : SDSA5322		V3	Checked : Shin Chi P.1/4



❖ MG



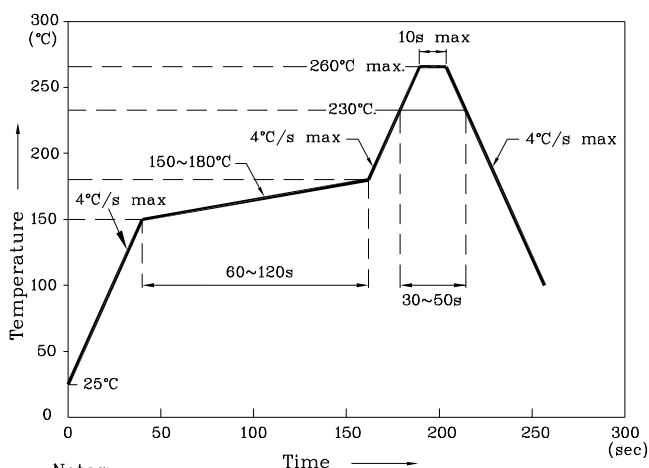
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

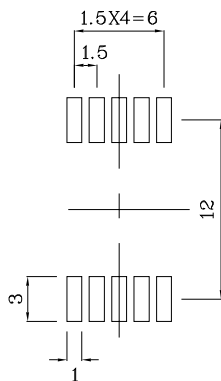
Reflow Soldering Profile For Lead-free SMT Process.



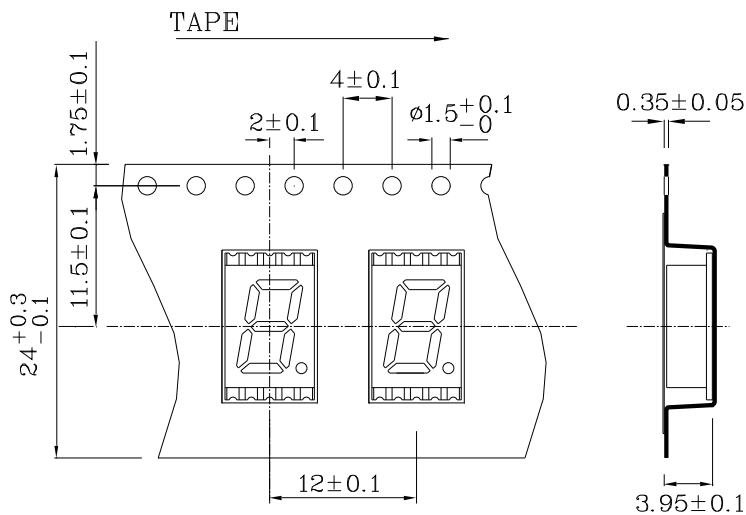
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:± 0.15)



❖ Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS ZFMG07C

